

DESIGN/PROCESS CHANGE NOTIFICATION

This is to inform you that a change is being made to the following products.

This is a minor change that has no impact on product quality, reliability, electrical or mechanical performance. Affected products will remain fully compliant to all published specifications. Notification is being made for informational purposes only and there is no approval required. Products incorporating this change may be shipped interchangeably with existing unchanged products.

Please contact your local Customer Quality Engineer if you have any questions regarding this notification. Alternatively, you may send an email request for information to PCNSupport@fairchildsemi.com.

Implementation of change:

Expected First Shipment Date for Changed Product : N/A

Expected First Date Code of Changed Product : N/A

Description of Change (From) :

Assembly and test of non low-Halogen, epoxy mold compound (EMC) devices at Fairchild Semiconductor Penang Malaysia (FSPM) per P1B8A.

Description of Change (To) :

Cancellation of P1B8A. Assembly and test will remain at Subcon China PSTS for non low-Halogen, epoxy mold compound (EMC) devices.

Reason for Change:

Re-allocation of available capacity to PCK HVIC 8SOP PSTS in-sourcing project.

Affected Product(s):

FAN73611MX	FAN7361MX	FAN7362MX
FAN73711MX	FAN7371MX	FAN7380MX
FAN7380MX_WS	FAN7382MX	FAN7382MX_WS
FAN73832MX	FAN73833MX	FAN7387MX
FAN73901MX	FAN7390MX	FAN73932MX
FAN7601BMX	FAN7711MX	FAN7711SMX
FAN7711ZMX	FAN7842MX	KA34063ADTF
MC33063ADX	MC34063AD	